Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2 X 2 X 0.55 (1 X 1.6 EP)
Lead Count	8
Terminal Finish	NiPdAu
MS Number	MS010676B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.00E-03	83.25	832500	34.46	344635
Thermosets	Epoxy resin	158117-90-9 / 85954-11-6	3.25E-04	5.42	54200	2.24	22437
Thermosets	Phenol resin	26834-02-6	2.07E-04	3.45	34500	1.43	14282
Other inorganic materials	Metal Hydroxide	1309-42-8 / 20427-58-1	3.25E-04	5.42	54200	2.24	22437
Others	Others	Proprietary	1.48E-04	2.46	24600	1.02	10184
Subtotal			6.00E-03	100.00	1000000	41.40	413976

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.25 E-03	96.20	962000	36.24	362397
Copper & its alloys	Nickel	7440-02-0	1.64 E-04	3.00	30000	1.13	11301
Copper & its alloys	Silicon	7440-21-3	3.55 E-05	0.65	6500	0.24	2449
Copper & its alloys	Magnesium	7439-95-4	8.19 E-06	0.15	1500	0.06	565
Subtotal			5.46 E-03	100.00	1000000	37.67	376712

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.97 E-04	95.02	950185	2.05	20512
Precious metals	Palladium	7440-05-3	1.27 E-05	4.06	40590	0.09	876
Precious metals	Gold	7440-57-5	2.89 E-06	0.92	9225	0.020	199
Subtotal			3.13 E-04	100.00	1000000	2.16	21588

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.14 E-05	100.0	1000000	0.49	4924

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.57 E-03	100.0	1000000	17.73	177305

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.13 E-05	77.00	770000	0.42	4231
Other organic materials	Acrylic resin	Proprietary	5.57 E-06	7.00	70000	0.04	385
Other organic materials	Acrylate	Proprietary	4.38 E-06	5.50	55000	0.03	302
Other organic materials	Polybutadiene derivative	Proprietary	3.58 E-06	4.50	45000	0.02	247
Thermoset	Epoxy resin	Proprietary	1.99 E-06	2.50	25000	0.01	137
Other organic materials	Butadiene Copolymer	Proprietary	1.19 E-06	1.50	15000	0.01	82
Others	Additive	Proprietary	1.19 E-06	1.50	15000	0.01	82
Others	Peroxide	Proprietary	3.98 E-07	0.50	5000	0.003	27
Subtotal			7.96 E-05	100.0	1000000	0.55	5495

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.45 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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